

ABSTRACT

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5 An underfilling material for a semiconductor package
holding semiconductor elements on a carrier substrate mounted
on a circuit board, containing a one-pack type thermosetting
urethane composition which preferably comprises a urethane
prepolymer having a terminal isocyanate group, which is obtained
by reacting a polyol with an excessive amount of a polyisocyanate,
and a fine powder-coated curing agent comprising a curing agent
which is in a solid state at room temperature and surface active
10 sites of which are covered with a fine powder. This composition
can achieve both the low temperature curing properties and the
storage stability.